S/N 10/023,8192 PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Biju Chandran et al. Examiner: John Vigushin

Serial No.: 10/023,819 Group Art Unit: 2827

Filed: December 21, 2001 Docket: 884.A27US1

Title: CHIP-JOIN PROCESS TO REDUCE ELONGATION MISMATCH BETWEEN

THE ADHERENTS AND SEMICONDUCTOR PACKAGE MADE THEREBY

Assignee: Intel Corporation Customer No: 21186

## **INFORMATION DISCLOSURE STATEMENT**

U.S. Patent and Trademark Office 220 20<sup>th</sup> Street South, Customer Window, **Mail Stop 313(c)** Crystal Plaza Two, Lobby, Room 1B03 Arlington, VA 22202

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(b), it is believed that no fee or statement is required with the Information Disclosure Statement. However, if an Office Action on the merits has been mailed, the Commissioner is hereby authorized to charge the required fees to Deposit Account No. 19-0743 in order to have this Information Disclosure Statement considered.

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Assignee: Intel Corporation

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

BIJU CHANDRAN ET AL.

By their Representatives,

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Date Oct. 21, 2004

Ann M. McCrackin Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being hand-delivered to: U.S. Patent and Trademark Office, 220 20th Street South, Customer Window, Mail Stop 313(c), Crystal Plaza Two, Lobby, Room 1B03, Arlington, VA 22202, on this 22nd day of October, 2004.

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Inder the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number. Substitute for form 1449A/PTO Complete if Known INFORMATION DISCLOSURE 10/023,819 **Application Number** STATEMENT BY APPLICANT December 21, 2001 (Use as many sheets as necessary) **Filing Date** Chandran, Biju **First Named Inventor** 2827 **Group Art Unit** Vigushin, John **Examiner Name** Attorney Docket No: 884.A27US1 Sheet 1 of 1 BADEN

	US PATENT DOCUMENTS									
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	OTHE	R DOCUMENTS NON PATENT LITERATURE DOCUMENTS	
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